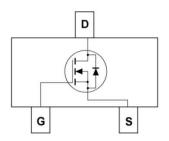


N-Channel Enhancement Mode MOSFET

Feature

- 16V/6A, $R_{DS(ON)} = 50 \text{m} \Omega \text{ (MAX) @V_{GS}} = 4.5 \text{V}.$ $R_{DS(ON)} = 55 \text{m} \Omega \text{ (MAX) @V_{GS}} = 2.5 \text{V}.$
- Super High dense cell design for extremely low RDS(ON).
- Reliable and Rugged.
- SC-59 for Surface Mount Package .



Applications

LI-ION Protection Circuit

Absolute Maximum Ratings Ta=25 °C Unless Otherwise noted

Parameter	Symbol	Limit	Units	
Drain-Source Voltage	V_{DS}	16	V	
Gate-Source Voltage	V_{GS}	±12	V	
Drain Current-Continuous	I _D	6	A	

Electrical Characteristics TA=25° Unless Otherwise noted

Parameter	Symbol	Test Conditions	Min	Тур.	Max	Units		
Off Characteristics								
Drain to Source Breakdown Voltage	BVDSS	VGS=0V, ID=250 µA	16	-	-	V		
Zero-Gate Voltage Drain Current	IDSS	VDS=6V, VGS=0V	-	-	1	μA		
Gate Body Leakage Current, Forward	IGSSF	VGS=12V, VDS=0V	-	-	300	пA		
Gate Body Leakage Current, Reverse	IGSSR	VGS=12V, VDS=0V	-	-	-300	пA		
On Characteristics								
Gate Threshold Voltage	VGS(th)	VGS= VDS, ID=250μA	0.4	-	1.3	V		
Static Drain-source	RDS(ON)	VGS =4.5V, ID =6.0A	-	40	50	mΩ		
On-Resistance		VGS =2.5V, ID =5.2A	-	44	55	$\mathbf{m} \Omega$		
Drain-Source Diode Characteristics and Maximum Ratings								
Drain-Source Diode Forward Voltage	VSD	VGS =0V, IS=1.5A			1.2	V		

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Typical Characteristics

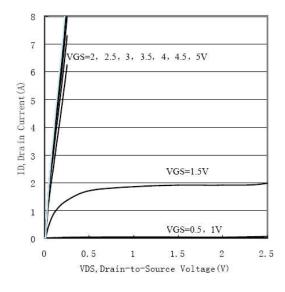


Figure 1. Output Characteristics

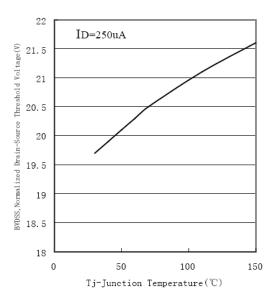


Figure 3. Breakdown Voltage Variation with Temperature

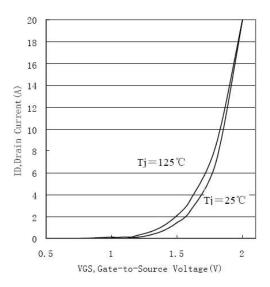


Figure 2. Transfer Characteristics

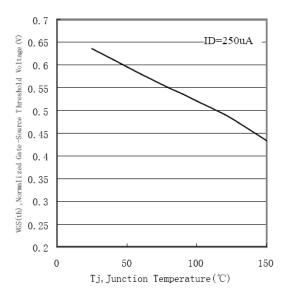
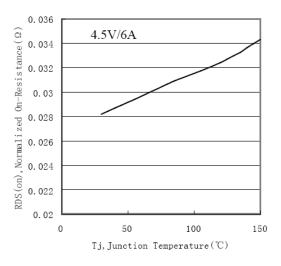
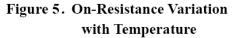


Figure 4. Gate Threshold Variation with Temperature







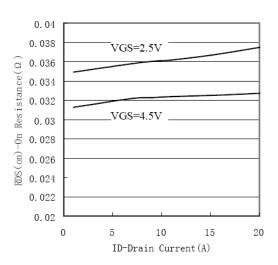


Figure 6. On-Resistance vs. Drain Current

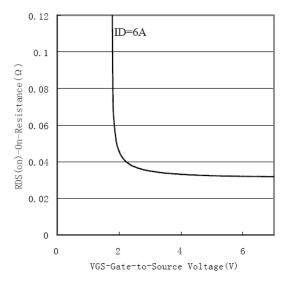


Figure 7. On-Resistance vs. Gate-to-Source Voltage

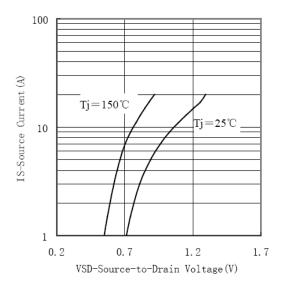


Figure 8. Source-Drain Diode Forward Voltage

单击下面可查看定价,库存,交付和生命周期等信息

>>SHIKUES(时科)